

**Amendments to the Claims:**

Please cancel claims 1 to 10 as presented in the underlying International Application No. PCT/DE2004/00812.

Please add new claims 11 to 22 as indicated in the listing of claims below.

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1 to 10 (cancelled).

Claim 11 (new):        A method for processing one or more components of gas turbines prior to and/or during further processing of same, comprising heating a component of a gas turbine with at least one laser device.

Claim 12 (new):        The method as recited in Claim 11, wherein the component is irradiated at least on one side by the at least one laser device.

Claim 13 (new):        The method as recited in Claim 11, wherein the at least one laser device includes a first laser device and a second laser device, and wherein the step of heating comprises irradiating the component on two sides from two irradiation directions using laser radiation, the first laser device being used for one irradiation direction and the second laser device being used for the other irradiation direction.

Claim 14 (new):        The method as recited in Claim 11, wherein the at least one laser device includes a plurality of laser devices, and wherein the step of heating comprises irradiating the components on all sides from multiple irradiation directions using laser radiation, one laser device being used for each irradiation direction.

Claim 15 (new): The method as recited in Claim 11, further comprising adjusting angles of incidence at which laser radiation hit a surface of the component to the contour of said surface.

Claim 16 (new): The method as recited in Claim 14, further comprising adjusting angles of incidence at which laser radiation from the plurality of laser devices hit a plurality of surfaces of the component to the contour of each surface.

Claim 17 (new): The method as recited in Claim 11, further comprising measuring a temperature of the component, and, as a function thereof, adjusting such the power of the laser device to achieve an intended temperature setpoint value.

Claim 18 (new): The method as recited in Claim 14, further comprising measuring a temperature of the component, and, as a function thereof, adjusting such the power of each laser device to achieve an intended temperature setpoint value.

Claim 19 (new): The method as recited in Claim 17, wherein the heating and measuring steps are performed without contacting the component.

Claim 20 (new): The method as recited in Claim 11, wherein one or multiple diode laser(s) are used as the at least one laser device.

Claim 21 (new): The method as recited in Claim 11, further comprising subjecting the component to further processing after or during heating.

Claim 22 (new): The method as recited in Claim 19, wherein the further processing comprises laser hardfacing the component with a separate laser device.